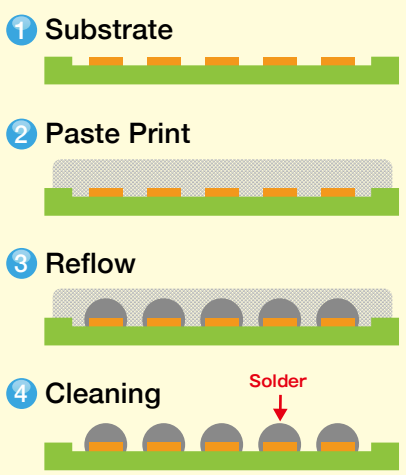
Super Solder (SS)、SAC-N、SAC-U series
~Lead-free paste for fine-pitch bump~

Fine-pitch soldering materials for peripheral substrate (Super Solder) and fine-pitch area array substrate(SAC-N, SAC-U series).

Peripheral Substrate / Whole Surface Print Method

Precoating Process

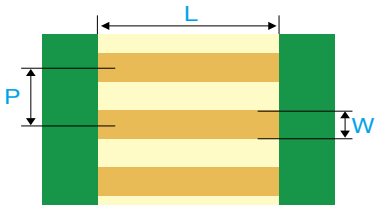


Precoating Examples※

(unit:μm)

Condition	1	2	3	4
Electrode shape	Straight			
Arrangement	In-Line		Staggered	
Pitch, P	60	50	35	30
Length, L	120	80	140	120
Width, W	30	20	35	30
Mean bump height	14	12	14	13
STD	1.4	1.3	1.4	1.3

※)Representative values (not guaranteed)

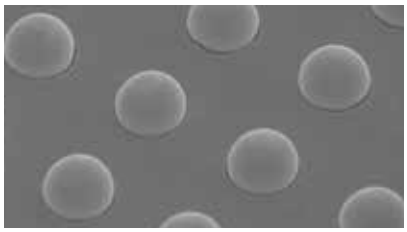


P : Pitch L : SR opening length
W : Pad width

▲ 50 μm-pitch substrate Precoated Solder

Bump Formation : Fine-pitch Capability & Ultra Low-alpha Emission

Solder Bump Formation by SAC-U-330(150μm pitch Substrate)



- Mean Bump Height : 35μm※
- STD : 2

※Representative values (not guaranteed)

Application	Fine-pitch Area Array Bump		Ultra- fine-pitch Area Array Bump	
Product Name	SAC-N-400	SAC-U-600	SAC-N-110	SAC-U-330
Ultra Low α	Non Compliant	Compliant	Non Compliant	Compliant
α Emission Count	high α	< 0.002 cph/cm²	high α	< 0.002 cph/cm²
Alloy Composition	Sn-3.0Ag-0.5Cu		Sn-3.0Ag-0.5Cu	
Melting Point	220 ℃		220 ℃	
Particle Size	5-15 μm		1-10 μm	
Viscosity	280 Pa·s		300 Pa·s	